ICS 33.120.20, 33.120.30, 35.200

SLOVENSKÁ TECHNICKÁ NORMA

Júl 2021

STN	**Rozhrania univerzálnej sériovej zbernice pre dáta a napájanie Časť 1-3: Spoločné súčasti Špecifikácia USB kábla a konektora typu C**	**STN EN IEC 62680-1-3 36 8365**

Universal serial bus interfaces for data and power - Part 1-3: Common components - USB Type-C Cable and Connector Specification

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 06/21

Obsahuje: EN IEC 62680-1-3:2021, IEC 62680-1-3:2021

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 62680-1-3

March 2021

ICS 33.120.20; 33.120.30; 35.200

Supersedes EN IEC 62680-1-3:2018 and all of its amendments and corrigenda (if any)

English Version

Universal serial bus interfaces for data and power - Part 1-3: Common components - USB Type-C(r) Cable and Connector Specification (IEC 62680-1-3:2021)

Interfaces de bus universel en série pour les données et l'alimentation électrique - Partie 1-3: Composants communs - Spécification des câbles et connecteurs USB Type-C(r) (IEC 62680-1-3:2021)

Schnittstellen des Universellen Seriellen Busses für Daten und Energie - Teil 1-3: Gemeinsame Bauteile - Festlegung für USB-Typ-CTM-Kabel und -Steckverbinder (IEC 62680-1-3:2021)

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European foreword

The text of document 100/3439/CDV, future edition 4 of IEC 62680-1-3, prepared by IEC/TC 100 "Audio, video and multimedia systems and equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62680-1-3:2021.

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IEC 62680-1-3

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Universal serial bus interfaces for data and power – Part 1-3: Common components – USB Type-C® Cable and Connector Specification

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UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER

Part 1-3: Common components – USB Type-C® Cable and Connector Specification

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The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this International Standard is based on the following documents:

CDV	Report on voting
100/3439/CDV	100/3501/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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INTRODUCTION

The IEC 62680 series is based on a series of specifications that were originally developed by the USB Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of a special agreement between the IEC and the USB-IF.

This standard is the USB-IF publication Universal Serial Bus Type-C Cable and Connector Specification Revision 2.0.

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Universal Serial Bus Type-C® Cable and Connector Specification

Release 2.0
August 2019

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Revision History

Revision	Date	Description
1.0	August 11, 2014	Initial Release
1.1	April 3, 2015	Reprint release including incorporation of all approved ECNs as of the revision date plus editorial clean-up.
1.2	March 25, 2016	Reprint release including incorporation of all approved ECNs as of the revision date plus editorial clean-up.
1.3	July 14, 2017	Reprint release including incorporation of all approved ECNs as of the revision date plus editorial clean-up.
1.4	March 29, 2019	Reprint release including incorporation of all approved ECNs as of the revision date plus editorial clean-up.
2.0	August 2019	New release primarily for enabling USB4 over USB Type-C connectors and cables. Also includes incorporation of all approved ECNs as of the revision date plus editorial clean-up.

1 Introduction

With the continued success of the USB interface, there exists a need to adapt USB technology to serve newer computing platforms and devices as they trend toward smaller, thinner and lighter form-factors. Many of these newer platforms and devices are reaching a point where existing USB receptacles and plugs are inhibiting innovation, especially given the relatively large size and internal volume constraints of the Standard-A and Standard-B versions of USB connectors. Additionally, as platform usage models have evolved, usability and robustness requirements have advanced and the existing set of USB connectors were not originally designed for some of these newer requirements. This specification is to establish a new USB connector ecosystem that addresses the evolving needs of platforms and devices while retaining all of the functional benefits of USB that form the basis for this most popular of computing device interconnects.

1.1 Purpose

This specification defines the USB Type-C® receptacles, plug and cables.

The USB Type-C Cable and Connector Specification is guided by the following principles:

- Enable new and exciting host and device form-factors where size, industrial design and style are important parameters
- Work seamlessly with existing USB host and device silicon solutions
- Enhance ease of use for connecting USB devices with a focus on minimizing user confusion for plug and cable orientation

The USB Type-C Cable and Connector Specification defines a new receptacle, plug, cable and detection mechanisms that are compatible with existing USB interface electrical and functional specifications. This specification covers the following aspects that are needed to produce and use this new USB cable/connector solution in newer platforms and devices, and that interoperate with existing platforms and devices:

- USB Type-C receptacles, including electro-mechanical definition and performance requirements
- USB Type-C plugs and cable assemblies, including electro-mechanical definition and performance requirements
- USB Type-C to legacy cable assemblies and adapters
- USB Type-C-based device detection and interface configuration, including support for legacy connections
- USB Power Delivery optimized for the USB Type-C connector

The USB Type-C Cable and Connector Specification defines a standardized mechanism that supports Alternate Modes, such as repurposing the connector for docking-specific applications.

1.2 Scope

This specification is intended as a supplement to the existing *USB 2.0*, *USB 3.2*, *USB4™* and *USB Power Delivery* specifications. It addresses only the elements required to implement and support the USB Type-C receptacles, plugs and cables.

Normative information is provided to allow interoperability of components designed to this specification. Informative information, when provided, may illustrate possible design implementations.

1.3 Related Documents

USB 2.0 *Universal Serial Bus Revision 2.0 Specification*
This includes the entire document release package.

USB 3.2 *Universal Serial Bus Revision 3.2 Specification*
This includes the entire document release package.
USB 3.1 Legacy Cable and Connector Specification, Revision 1.0

USB4 *USB4™ Specification, Version 1.0, August 2019 (including posted errata and ECNs)*

TBT3 Chapter 13 of *USB4 Specification, Version 1.0, August 2019*

USB PD *USB Power Delivery Specification, Revision 2.0, Version 1.3, January 12, 2017*
USB Power Delivery Specification, Revision 3.0, Version 2.0, August 2019 (including posted errata and ECNs)

USB BB *USB Billboard Device Class Specification, Revision 1.21, September 8, 2016*

USB BC *Battery Charging Specification, Revision 1.2 (including errata and ECNs through March 15, 2012), March 15, 2012*

DP AM *DisplayPort™ Alt Mode on USB Type-C Standard, Version 1.0b, 03 November 2017*

All USB-specific documents are available for download at http://www.usb.org/documents. The DisplayPort Alt Mode specification is available from VESA (http://www.vesa.org).